

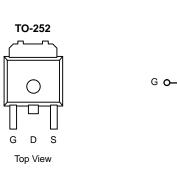
5890NG-VB Datasheet

N-Channel 40-V (D-S) MOSFET

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PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^{a, c}	Q _g (Typ.)			
40	0.0016 at V _{GS} = 10 V	120	120 nC			
	0.0020 at V _{GS} = 4.5 V	100	120110			
			D			



FEATURES

- Trench Power MOSFET
- 100 % R_g and UIS Tested

APPLICATIONS

- Synchronous Rectification
- Power Supplies

ABSOLUTE MAXIMUM RATING	S T _A = 25 °C, unles	ss otherwise note	ed		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	40	V		
Gate-Source Voltage	V _{GS}	± 25			
	T _C = 25 °C		120 ^{a, c}		
Continuous Drain Current (T = $175 ^{\circ}\text{C}$)	T _C = 70 °C		96 ^c		
Continuous Drain Current ($T_J = 175 \ ^{\circ}C$)	T _A = 25 °C	I _D	29 ^b	A	
	T _A = 70 °C		23 ^b		
Pulsed Drain Current	I _{DM}	250			
Avalanche Current Pulse	anche Current Pulse			96	
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	320	mJ	
Continuous Course Drain Diada Current	T _C = 25 °C	1	120 ^{a, c}		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	2.6 ^b	— A	
	T _C = 25 °C		312 ^a		
Marian Branco Dissinguia	T _C = 70 °C		200		
Maximum Power Dissipation	T _A = 25 °C	P _D	3.13 ^b	W	
	T _A = 70 °C		2.0 ^b		
Operating Junction and Storage Temperature R	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^b	Steady State	R _{thJA}	32	40	°C/W		
Maximum Junction-to-Case	Steady State	R _{thJC}	0.33	0.4	C/W		

Notes:

a. Based on $T_C = 25 \ ^{\circ}C$.

b. Surface Mounted on 1" x 1" FR4 board.

c. Calculated based on maximum junction temperature. Package limitation current is 120 A.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V$, $I_{D} = 250 \mu A$	40			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		41		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \mu A$		- 8		mv/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.2		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zara Cata Valtaga Drain Current	la e e	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$	40 40 41 -8 1.20 1.80 650 450 1.20 3.0 1.120 3.0 1.120 3.0 1.120 3.0 1.120 3.0 1.11 1.11 1.12 1.11 1.12 1.11 1.12 1.11 1.10	1	μA		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 40$ V, $V_{GS} = 0$ V, $T_{J} = 55$ °C		10			
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5$ V, V_{GS} = 10 V	120			А	
Drain Course On State Desistenced	P	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 30 \text{ A}$	0.001			0	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		0.0020		Ω	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 30 \text{ A}$		180		S	
Dynamic ^b							
Input Capacitance	C _{iss}			9000		pF	
Output Capacitance	C _{oss}	V_{DS} = 20 V, V_{GS} = 0 V, f = 1 MHz		650			
Reverse Transfer Capacitance	C _{rss}			450			
Total Gate Charge	Qg			120	180	nC	
Gate-Source Charge	Q _{gs}	V_{DS} = 20 V, V_{GS} = 10 V, I_{D} = 20 A		30			
Gate-Drain Charge	Q _{gd}			16		1	
Gate Resistance	Rg	f = 1 MHz		0.85	1.3	Ω	
Turn-On Delay Time	t _{d(on)}			20	30		
Rise Time	t _r	V_{DD} = 20 V, R _L = 1.0 Ω		11	17	1	
Turn-Off Delay Time	t _{d(off)}	$\text{I}_{\text{D}}\cong$ 20 A, V_{GEN} = 10 V, R_{g} = 1 Ω		77	115		
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			102	155	ns	
Rise Time	t _r	V_{DD} = 20 V, R_L = 1.0 Ω		62	95	-	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ 20 A, V_{GEN} = 4.5 V, R_g = 1 Ω		180	270		
Fall Time	t _f			60	90		
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			110	•	
Pulse Diode Forward Current ^a	I _{SM}				200	A	
Body Diode Voltage	V _{SD}	I _S = 20 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			50	75	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 20 A, di/dt = 100 A/μs, T _J = 25 °C		70	105	nC	
Reverse Recovery Fall Time	ta			30			
Reverse Recovery Rise Time	t _b			20		ns	

Notes:

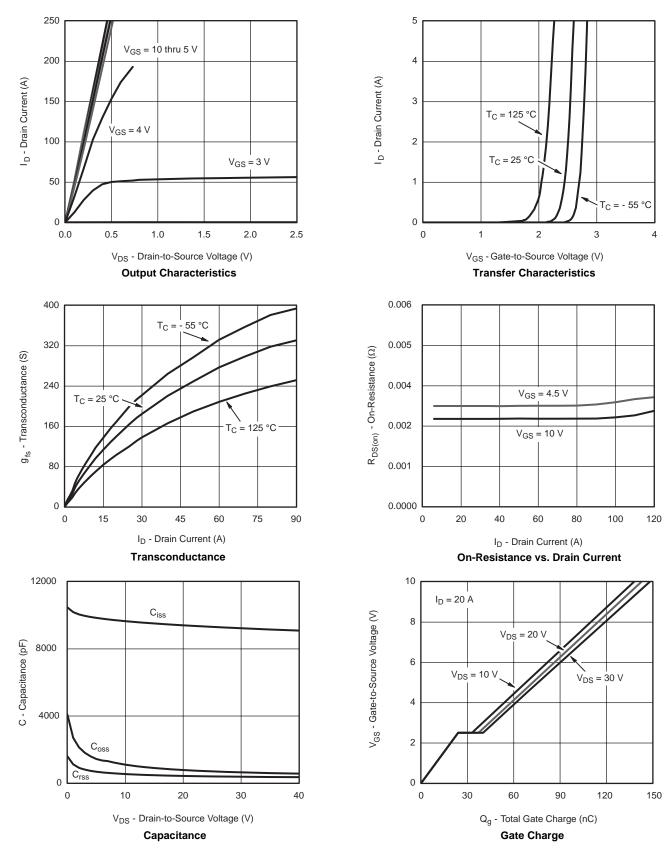
a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle ≤ 2 %.

b. Guaranteed by design, not subject to production testing.

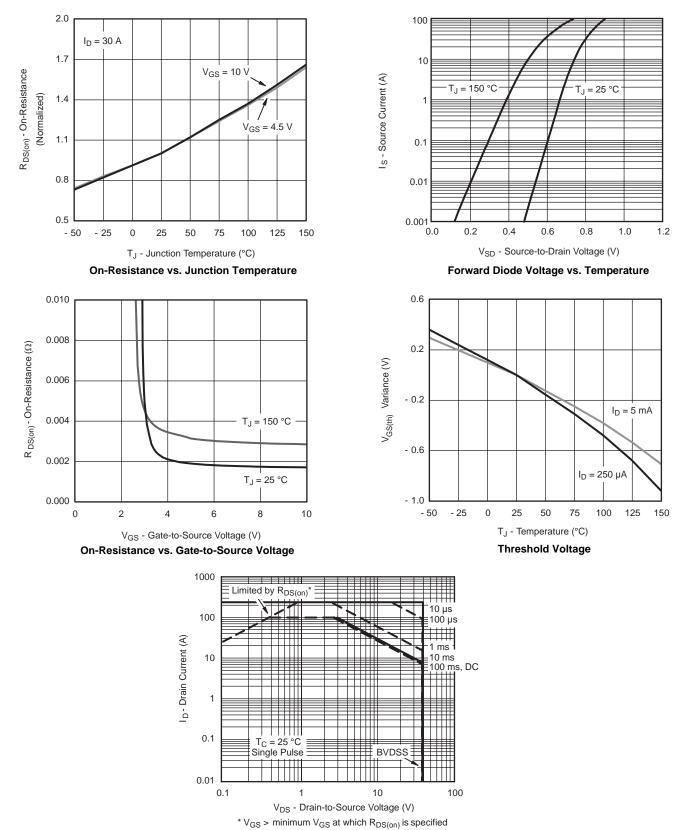
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.







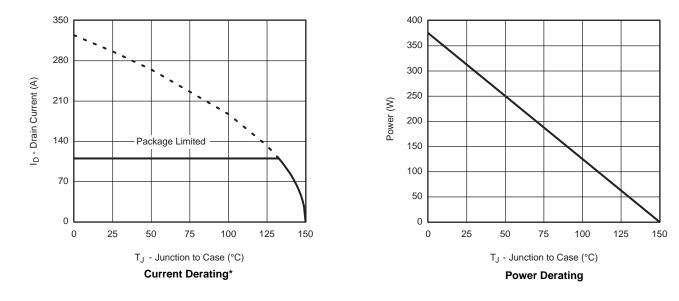




Safe Operating Area, Junction-to-Ambient

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





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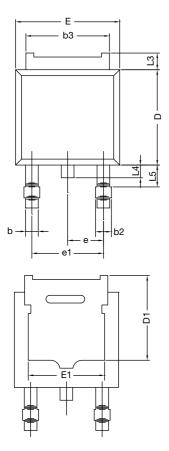
* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

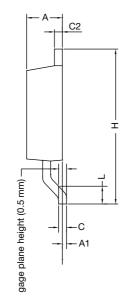


Normalized Thermal Transient Impedance, Junction-to-Case



TO-252AA CASE OUTLINE





	MILLIMETERS		INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
E	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090 BSC		
e1	4.56 BSC		0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347					

Note

• Dimension L3 is for reference only.



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